HUFA75639S3ST-F085A

Absolute Maximum Ratings $T_C = 25^{\circ}C$, Unless Otherwise Specified

		UNITS
Drain to Source Voltage (Note 1)	100	V
Drain to Gate Voltage ($R_{GS} = 20k\Omega$) (Note 1)	100	V
Gate to Source Voltage	±20	V
Drain Current		
Continuous (Figure 2)	56	Α
Pulsed Drain Current	Figure 4	
Pulsed Avalanche Rating E _{AS}	Figures 6, 14, 15	
Power Dissipation	200	W
Derate Above 25 ^o C	1.35	W/oC
Operating and Storage Temperature	-55 to 175	°C
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10sT _L	300	°C
Package Body for 10s, See Techbrief 334	260	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE

1. $T_J = 25^{\circ}C$ to $150^{\circ}C$.

Electrical Specifications $T_C = 25^{\circ}C$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST	CONDITIONS	MIN	TYP	MAX	UNITS
OFF STATE SPECIFICATIONS	*			*			
Drain to Source Breakdown Voltage	BV _{DSS}	$I_D = 250 \mu A, V_{GS} =$	100	-	-	V	
Zero Gate Voltage Drain Current	I _{DSS} V _{DS} = 95V, V _{GS} = 0		0V	-	-	1	μΑ
		V _{DS} = 90V, V _{GS} =	-	-	250	μΑ	
Gate to Source Leakage Current	I _{GSS}	V _{GS} = ±20V	-	-	±100	nA	
ON STATE SPECIFICATIONS		1		J.			
Gate to Source Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 2$	2	-	4	V	
Drain to Source On Resistance	r _{DS(ON)}	I _D = 56A, V _{GS} = 10	-	0.021	0.025	Ω	
THERMAL SPECIFICATIONS	-1	1		1	1	II.	
Thermal Resistance Junction to Case	$R_{\theta JC}$	(Figure 3)		-	-	0.74	oC/W
Thermal Resistance Junction to Ambient	R _{θJA} TO-247			-	-	30	oC/W
		TO-220, TO-263		-	-	62	oC/W
SWITCHING SPECIFICATIONS (VGS = 10)V)	1		J.			
Turn-On Time	t _{ON}	V _{DD} = 50V, I _D ≅ 56	-	-	110	ns	
Turn-On Delay Time	t _d (ON)	$R_L = 0.89\Omega, V_{GS} = 10V,$ $R_{GS} = 5.1\Omega$		-	15	-	ns
Rise Time	t _r		-	60	-	ns	
Turn-Off Delay Time	t _d (OFF)		-	20	-	ns	
Fall Time	t _f		-	25	-	ns	
Turn-Off Time	tOFF		-	-	70	ns	
GATE CHARGE SPECIFICATIONS		-				Į.	
Total Gate Charge	Q _{g(TOT)}	V _{GS} = 0V to 20V	V _{DD} = 50V,	-	110	130	nC
Gate Charge at 10V	Q _{g(10)}	V _{GS} = 0V to 10V	$I_D \cong 56A$, $R_1 = 0.89\Omega$	-	57	75	nC
Threshold Gate Charge	Q _{g(TH)}	V _{GS} = 0V to 2V	$I_{g(REF)} = 1.0mA$	-	3.7	4.5	nC
Gate to Source Gate Charge	Q _{gs}		(Figure 13)	-	9.8	-	nC
Gate to Drain "Miller" Charge	Q _{gd}			-	24	-	nC

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Electrical Specifications $T_C = 25^{\circ}C$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS	
CAPACITANCE SPECIFICATIONS							
Input Capacitance	C _{ISS}	$V_{DS} = 25V$, $V_{GS} = 0V$, f = 1MHz (Figure 12)	-	2000	-	pF	
Output Capacitance	C _{OSS}		-	500	-	pF	
Reverse Transfer Capacitance	C _{RSS}		-	65	-	pF	

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	V_{SD}	I _{SD} = 56A	-	-	1.25	V
Reverse Recovery Time	t _{rr}	$I_{SD} = 56A$, $dI_{SD}/dt = 100A/\mu s$	-	-	110	ns
Reverse Recovered Charge	Q_{RR}	$I_{SD} = 56A$, $dI_{SD}/dt = 100A/\mu s$	-	-	320	nC

Typical Performance Curves

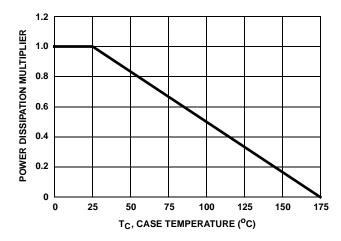


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

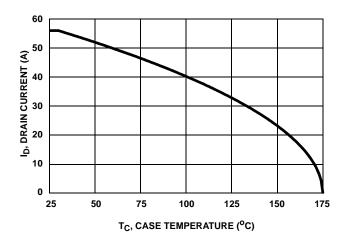


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

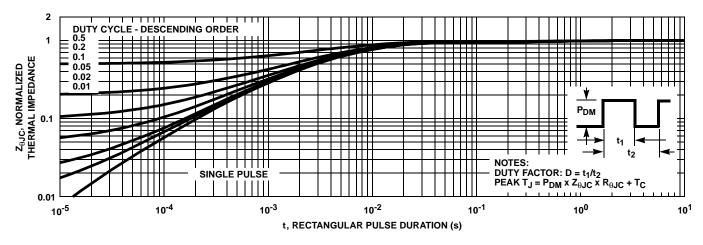


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

Typical Performance Curves (Continued)

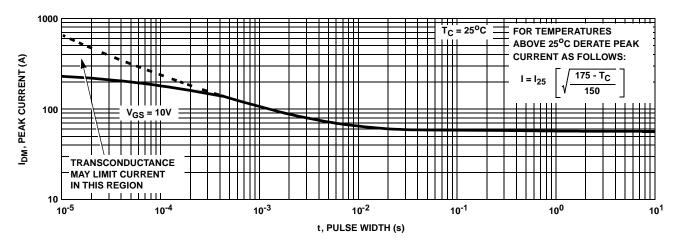


FIGURE 4. PEAK CURRENT CAPABILITY

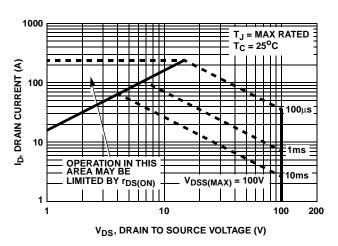
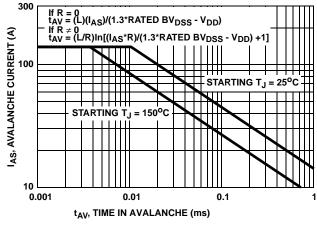


FIGURE 5. FORWARD BIAS SAFE OPERATING AREA



NOTE: Refer to ON Semiconductor Application Notes AN9321 and AN9322. FIGURE 6. UNCLAMPED INDUCTIVE SWITCHING CAPABILITY

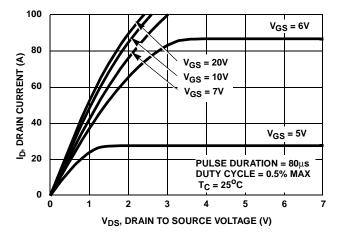


FIGURE 7. SATURATION CHARACTERISTICS

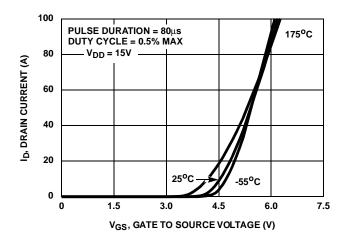


FIGURE 8. TRANSFER CHARACTERISTICS

Typical Performance Curves (Continued)

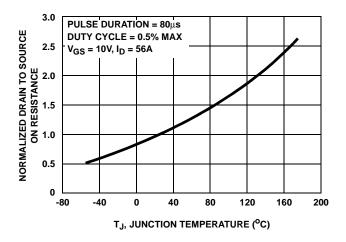


FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

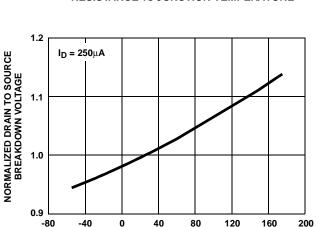


FIGURE 11. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

T_J, JUNCTION TEMPERATURE (°C)

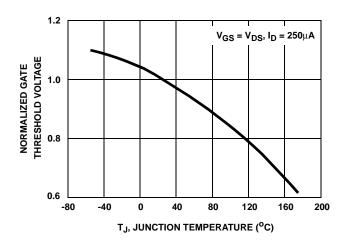


FIGURE 10. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

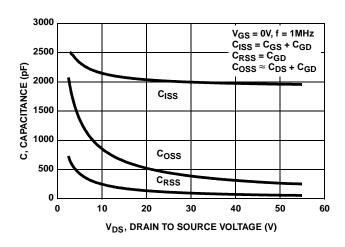
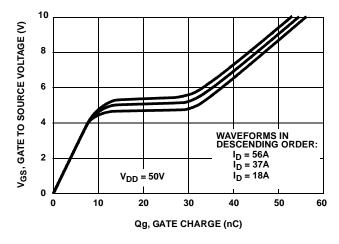


FIGURE 12. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to ON Semiconductor Application Notes AN7254 and AN7260.

FIGURE 13. GATE CHARGE WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms

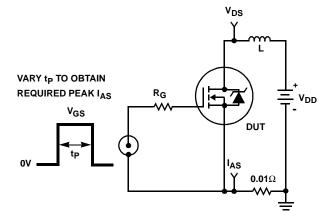


FIGURE 14. UNCLAMPED ENERGY TEST CIRCUIT

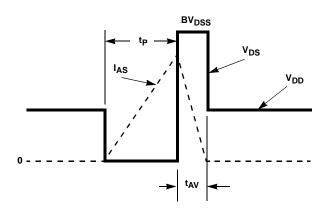


FIGURE 15. UNCLAMPED ENERGY WAVEFORMS

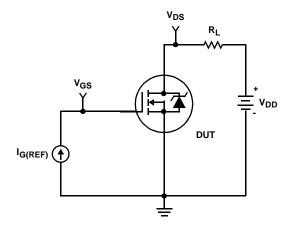


FIGURE 16. GATE CHARGE TEST CIRCUIT

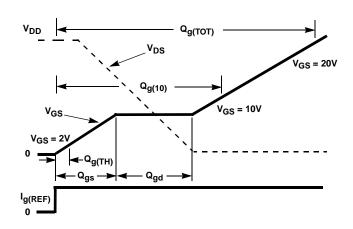


FIGURE 17. GATE CHARGE WAVEFORM

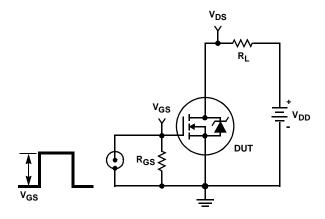


FIGURE 18. SWITCHING TIME TEST CIRCUIT

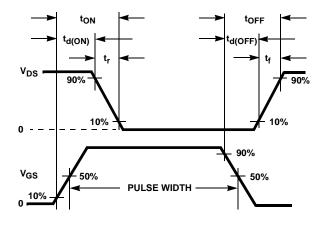


FIGURE 19. RESISTIVE SWITCHING WAVEFORMS

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